

Grades	XP01B/11B	XP03F	XP04A	H-100	H-200
Type	Dissolution	Dissolution	Dissolution	Dissolution	Dissolution
Base Polymer	Acid-modified Polyolefin				
Solid (%)	20	20	20	20	20
Viscosity (mPa · s)	120/180	90	90	160	420
Solvents	A: Cyclohexane / Ethylacetate B: Methylcyclohexane / Ethylacetate F: Methylcyclohexane / Butylacetate			MCH /Ethylacetate	MCH /Methylethylketone
Baking Temperature (°C)	A≥80°C、B≥100°C、F≥120°C			> 80	> 80
Heat Sealing Temperature (°C)	> 90 / > 100	> 90	> 90	> 100	> 140
Product Features	Standard/Higher Tm	Adhesion to Various Substrates	Adhesion to Various Substrates	Low Dielectric Constant	Higher Transparency

·The figures in the table above are typical values.